+2.5V to 5.5V, 230µA Dual Rail-to-Rail Voltage-Output DACs with Parallel Interface

Preliminary Technical Data AD5332/AD5333/AD5342/AD5343*

FEATURES

AD5332: Dual 8-Bit DAC in 20-Lead TSSOP AD5333: Dual 10-Bit DAC in 24-Lead TSSOP AD5342: Dual 12-Bit DAC in 28-Lead TSSOP AD5343: Dual 12-Bit DAC in 20-Lead TSSOP Micro-power Operation: 230µA@3V, 300µA@5V Power-Down to 80nA @3V, 200nA @5V +2.5V to +5.5V Power Supply **Double-Buffered Input Logic Guaranteed Monotonic by Design Over All Codes Buffered/Unbuffered Reference Input Options** 0-V_{REF} or 0-2V_{REF} Output Range Options **Power-On Reset to Zero Volts** Simultaneous Update of DAC Outputs via LDAC Asynchronous CLR facility Low Power Parallel Data Interface **On-Chip Rail-to-Rail Output Buffer Amplifiers**

APPLICATIONS

Portable Battery-Powered Instruments Digital Gain and Offset Adjustment Programmable Voltage and Current Sources Programmable Attenuators Industrial Process Control

GENERAL DESCRIPTION

The AD5332/AD5333/AD5342/AD5343 are dual 8-, 10and 12- bit DACs. They operate from a +2.5V to +5.5V supply consuming just 230 μ A at 3V and feature a powerdown mode which further reduces the current down to 80nA. These devices incorporate an on-chip output buffer which can drive the output to both supply rails, while the AD5333 and AD5342 allow a choice of buffered or unbuffered reference input.

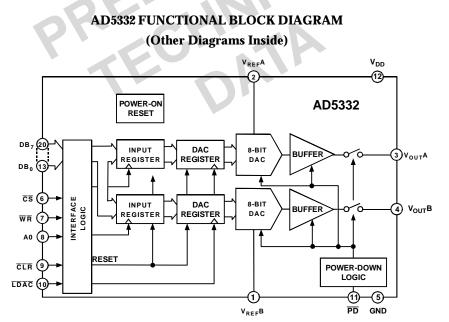
The AD5332/AD5333/AD5342/AD5343 have a parallel interface. \overline{CS} selects the device and data is loaded into the input registers on the rising edge of \overline{WR} .

The GAIN pin on the AD5333 and AD5342 allows the output range to be set at 0V to $V_{\rm REF}$ or 0V to 2 x $V_{\rm REF}.$

Input data to the DACs is double-buffered, allowing simultaneous update of multiple DACs in a system using the $\overline{\text{LDAC}}$ pin.

An asynchonous $\overline{\text{CLR}}$ input is also provided, which resets the contents of the Input Register and the DAC Register to all zeros. These devices also incorporate a power-onreset circuit that ensures that the DAC output powers on to 0V and remains there until valid data is written to the device.

The AD5332/AD5333/AD5342/AD5343 are available in Thin Shrink Small Outline Packages (TSSOP).



*Protected by U.S. Patent Number 5684481; other patents pending.

REV. PrD 12/99

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$\label{eq:stable} \begin{array}{l} AD5332/AD5333/AD5342/AD5343-SPECIFICATIONS \\ (v_{\text{DD}}=+2.5V \text{ to }+5.5V, \, v_{\text{REF}}=+2V. \, \text{DAC outputs unloaded. All specifications T_{MIN} to T_{MAX} unless otherwise noted). \end{array}$

Parameter ¹		B Version		Units	Conditions/Comments
	Min	Тур	Max		
DC PERFORMANCE ³					
AD5332					
Resolution		8		Bits	
Relative Accuracy		± 0.15	± 1	LSB	
Differential Nonlinearity		± 0.02	± 0.25	LSB	Guaranteed Monotonic by design over all codes
AD5333					
Resolution		10		Bits	
Relative Accuracy		± 0.5	± 3	LSB	
Differential Nonlinearity		± 0.05	± 0.5	LSB	Guaranteed Monotonic by design over all codes
AD5342/AD5343					
Resolution		12		Bits	
Relative Accuracy		± 2	± 12	LSB	
Differential Nonlinearity		± 0.2	± 1	LSB	Guaranteed Monotonic by design over all codes
Offset Error		± 0.4	± 3	% of FSR	
Gain Error		± 0.15	± 1	% of FSR	
Lower Deadband ⁴		10	60	m V	Lower Deadband exists only if offset error is negative
Offset Error Drift ⁵		-12		ppm of FSR/°C	
Gain Error Drift ⁵		- 5		ppm of FSR/°C	
DC Power Supply Rejection Ratio ⁵		-60		d B	$\Delta V_{\rm DD} = \pm 10\%$
DC Crosstalk ⁵		30		μV	$R_L = 2k\Omega$ to GND, $2k\Omega$ to V_{DD} ; $C_L = 200pF$ to GND
DAC REFERENCE INPUT ⁵					
V_{REF} Input Range	1		V_{DD}	V	Buffered Reference (AD5333 and AD5342)
V REF Input Runge	0		V _{DD}	v V	Unbuffered Reference
V _{REF} Input Impedance	Ŭ	>10	• DD	MΩ	Buffered Reference (AD5333 and AD5342)
REF Input Impodation		180		kΩ	Unbuffered Reference. Gain=1. Input Impedance= R_{DAC}
		90		kΩ	Unbuffered Reference. Gain=2. Input Impedance= R_{DAC}
Reference Feedthrough		-90		dB	Frequency=10kHz
Channel-to-Channel Isolation		-80		dB	Frequency=10kHz (AD5334, AD5335 and AD5342)
OUTPUT CHARACTERISTICS ⁵					
Minimum Output Voltage ⁶		0.001		V min	Rail-to-rail operation.
Maximum Output Voltage ⁶		V _{DD} -0.001		V max	
DC Output Impedance		0.5		Ω	
Short Circuit Current		50		m A	$V_{DD} = +5V$
		20		m A	$V_{DD} = +3V$
Power-Up Time		$2.5 \\ 5$		μs	Coming out of Power-Down Mode. $V_{DD} = +5V$
		Э		μs	Coming out of Power-Down Mode. $V_{DD} = +3V$
LOGIC INPUTS ⁵					
Input Current		±1		μA	
V _{IL} , Input Low Voltage			0.8	V	$V_{\rm DD} = +5V \pm 10\%$
			0.6	V	$V_{\rm DD} = +3V \pm 10\%$
			0.5	V	$V_{\rm DD} = +2.5 V$
V _{IH} , Input High Voltage	2.4			V	$V_{\rm DD}=+5V~\pm10\%$
	2.1			V	$V_{\rm DD} = +3V \pm 10\%$
	2.0			V	$V_{\rm DD} = +2.5 V$
Pin Capacitance			3.5	pF	
POWER REQUIREMENTS					
V _{DD}	2.5		5.5	V	
I _{DD} (Normal Mode)					Note: I _{DD} Specification is valid for All DAC Codes.
$V_{\rm DD}$ = +4.5V to +5.5V		300	600	μA	All DACs Active and Excluding Load Currents.
$V_{\rm DD}$ = +2.5V to +3.6V		230	TBD	μA	All DACs in Unbuffered Mode. $V_{IH} = V_{DD}$, $V_{IL} = GND$.
					Idd increases by 50 μA at $V_{\rm REF}$ $>$ $V_{\rm DD}$ -100mV
					In Buffered Mode, extra current is typically x µA
I_{DD} (Power-Down Mode)					where $x = 5 \mu A + V_{REF}/R_{DAC}$
$V_{\rm DD}$ = $+4.5V$ to $+5.5V$		0.2	1	μA	
$V_{DD} = +2.5V$ to $+3.6V$	1	0.08	1	μA	1

NOTES

¹See Terminology (page9)

²Temperature range: B Version: -40° C to $+105^{\circ}$ C.

¹Scherichter ange: B Version: -40 C to +105 C. ³Linearity is tested using a reduced code range: AD5332 (code 8 to 255); AD5333 (code 28 to 1023); AD5342/AD5343 (code 115 to 4095) ⁴This corresponds to x codes. x = Deadband voltage/LSB size ⁵Guaranteed by Design and Characterization, not production tested. ⁶In order for the amplifier output to reach its minimum voltage, Offset Error must be negative. In order for the amplifier output to reach its maximum voltage, V_{REF}=V_{DD} and "Offset plus Gain" Error must be positive.

Specifications subject to change without notice.

Parameter ²	B	Version ³		Units	Conditions/Comments
	Min	Тур	Max		
Output Voltage Settling Time					$V_{REF} = +2V$. See Figure x
ÅD5332		6	8	μs	1/4 Scale to 3/4 Scale change (40 H to C0 H)
AD5333		7	9	μs	1/4 Scale to 3/4 Scale change (100 H to 300 H)
AD5342		8	10	μs	1/4 Scale to 3/4 Scale change (400 H to C00 H)
AD5343		8	10	μs	1/4 Scale to 3/4 Scale change (400 H to C00 H)
Slew Rate		0.7		V∕µs	
Major Code Transition Glitch Energy		12		nV-s	1 LSB change around major carry (01111 to 10000)
Digital Feedthrough		0.10		nV-s	
Digital Crosstalk		TBD		nV-s	
Analog Crosstalk		0.01		nV-s	
DAC-to-DAC Crosstalk		0.01		nV-s	
Multiplying Bandwidth		200		kHz	$V_{REF}=2V\pm0.1Vpp$. Unbuffered Mode
Total Harmonic Distortion		-70		d B	$V_{REF}=2.5V\pm0.1Vpp$. Frequency=10kHz.

NOTES:

¹Guaranteed by design and characterization, not production tested.

²See Terminology

 3B Version: Industrial temperature range -40°C. to +105°C.

Specifications subject to change without notice

TIMING CHARACTERISTICS¹ (V_{DD} = +2.5V to +5.5V, All specifications T_{MIN} to T_{MAX} unless otherwise noted).

Parameter ^{2,3}	Limit at T _{MIN} , T _{MAX} (B Version) ⁴	Units	Conditions/Comments
t_	0	ns min	$\overline{\text{CS}}$ to $\overline{\text{WR}}$ Setup Time
t ₂	0	ns min	$\overline{\text{CS}}$ to $\overline{\text{WR}}$ Hold Time
t ₃	20	ns min	WR Pulse Width
t_4	5	ns min	Data, GAIN, BUF, HBEN Setup Time
t ₅	4.5	ns min	Data GAIN, BUF, HBEN Hold Time
t ₆	.5	ns min	Synchronous Mode. WR Falling to LDAC Falling
t ₇	5	ns min	Synchronous Mode. LDAC Falling to WR Rising.
t ₈	4.5	ns min	Synchronous Mode. WR Rising to LDAC Rising.
t ₉	5	ns min	Asynchronous Mode. LDAC Rising to WR Rising
t ₁₀	4.5	ns min	Asynchronous Mode. WR Rising to LDAC Falling.
t ₁₁	20	ns min	LDAC Pulse Width
t ₁₂	20	ns min	CLR Pulse Width
t ₁₃	50	ns min	Time between WR cycles
t ₁₄	20	ns min	A0 Setup Time
t ₁₅	0	ns min	A0 Hold Time

NOTES:

¹Guaranteed by design and characterization, not production tested.

²See Terminology

³See Figure 1

⁴B Version: Industrial temperature range -40°C. to +105°C.

Specifications subject to change without notice

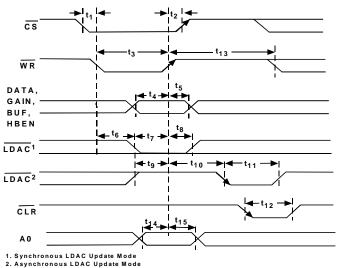


Figure 1. Parallel Interface Timing Diagram

ABSOLUTE MAXIMUM RATINGS*

$(T_A = +25^{\circ}C \text{ unless otherwise noted})$
V_{DD} to GND
Digital Input Voltage to GND0.3 V to V_{DD} + 0.3 V
Digital Output Voltage to GND \dots -0.3 V to V _{DD} + 0.3 V
Reference Input Voltage to GND0.3 V to V_{DD} + 0.3 V
V_{OUT} to GND
Operating Temperature Range
Industrial (B Version)40°C to +105°C
Storage Temperature Range65°C to +150°C
Junction Temperature+150°C
TSSOP Package
Power Dissipation $(T_J \text{ max} - T_A) / \theta_{JA} \text{ mW}$
Θ_{IA} Thermal Impedance (20-Lead TSSOP) 143°C/W
θ_{JA} Thermal Impedance (24-Lead TSSOP) 128°C/W
θ_{IA} Thermal Impedance (28-Lead TSSOP)97.9°C/W
θ_{JC} Thermal Impedance (20-Lead TSSOP) 45°C/W
θ _{JC} Thermal Impedance (24-Lead TSSOP) 42°C/W
θ_{IC} Thermal Impedance (28-Lead TSSOP) 14°C/W
Reflow Soldering
Peak Temperature
Time at Peak Temperature 10 sec to 40 sec
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NOTES

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION -

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD5332/AD5333/AD5342/AD5343 feature proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

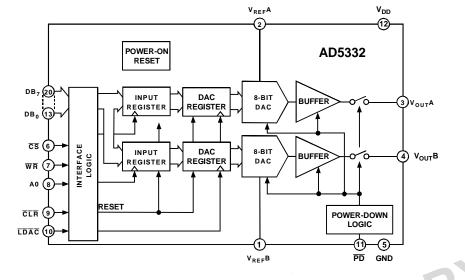
ORDERING GUIDE

Model	Temperature Range	Package Option*
AD5332BRU	-40°C to +105°C	RU-20
AD5333BRU	-40°C to +105°C	RU-24
AD5342BRU	-40°C to +105°C	RU-28
AD5343BRU	-40°C to +105°C	RU-20

*RU = TSSOP (Thin Shrink Small Outline Package)

NARY



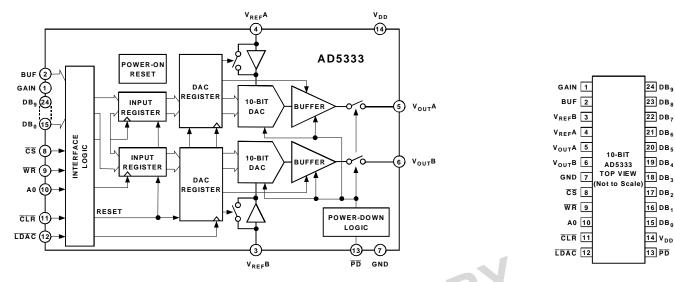


V _{REF} B 1		20 DB ₇
V _{REF} A 2		19 DB ₆
V _{OUT} A 3		18 DB ₅
V _{OUT} B 4		17 DB ₄
GND 5	8-BIT AD5332	16 DB ₃
CS 6	TOP VIEW (Not to Scale)	15 DB ₂
WR 7	(Not to ocale)	14 DB ₁
A0 8		13 DB ₀
CLR 9		12 V _{DD}
LDAC 10		11 PD

AD5332 PIN CONFIGURATION

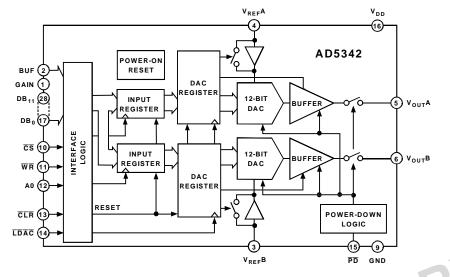
	AD5332 FUNCTIONAL BLOCK DIAGRAM AD5332 PIN CONFIGURATION							
AD5332	PIN FUNC	AD5332 PIN CONFIGURATION AD5332 PIN CONFIGURATION Function						
Pin No.	Mnemonic	Function						
1	V _{REF} B	Unbuffered reference input for DAC B.						
2	V _{REF} A	Unbuffered reference input for DAC A.						
3	V _{OUT} A	Output of DAC A. Buffered output with rail-to-rail operation.						
4	V _{OUT} B	Output of DAC B. Buffered output with rail-to-rail operation.						
5	GND	Ground reference point for all circuitry on the part.						
6	\overline{CS}	Active low Chip Select input. This is used in conjunction with \overline{WR} to write data to the parallel interface.						
7	$\overline{W}\overline{R}$	Active low Write input. This is used in conjunction with \overline{CS} to write data to the parallel interface.						
8	A0	Address pin for selecting between DAC A and DAC B.						
9	<u>C</u> LR	Asynchronous active-low control input which clears all input registers and DAC registers to zeroes.						
10	LDAC	Asynchronous active-low control input which updates the DAC registers with the contents of the input registers. This allows all DAC outputs to be simultaneously updated.						
11	PD	Power-Down pin. This active low control pin puts all DACs into power-down mode.						
12	V _{DD}	Power Supply pin. This part operated from +2.5V to +5.5V.						
13-20	DB ₀ -DB ₇	8 Parallel Data Inputs. DB7 is the MSB of these 8 bits.						

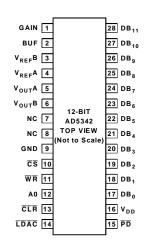
AD5332 PIN FUNCTION DESCRIPTION



A D 5 9 9 9		AD5333 PIN CONFIGURATION AD5333 PIN CONFIGURATION FUNCTION
Pin No.	Mnemonic	Function
1	GAIN	Gain control pin. This controls whether the output range from the DAC is $0\text{-}V_{REF}$ or $0\text{-}2V_{REF}$
2	BUF	Buffer control pin. This pin controls whether the reference input to the DAC is buffered or unbuffered.
3	V _{REF} B	Reference input for DAC B.
4	V _{REF} A	Reference input for DAC A.
5	V _{OUT} A	Output of DAC A. Buffered output with rail-to-rail operation.
6	V _{OUT} B	Output of DAC B. Buffered output with rail-to-rail operation.
7	GND	Ground reference point for all circuitry on the part.
8	$\overline{C}\overline{S}$	Active low Chip Select input. This is used in conjunction with \overline{WR} to write data to the parallel interface.
9	$\overline{W}\overline{R}$	Active low Write input. This is used in conjunction with \overline{CS} to write data to the parallel interface.
10	A0	Address pin for selecting between DAC A and DAC B.
11	\overline{CLR}	Asynchronous active-low control input which clears all input registers and DAC registers to zeroes.
12	ĪDĀC	Asynchronous active-low control input which updates the DAC registers with the contents of the input registers. This allows all DAC outputs to be simultaneously updated.
13	$\overline{P}\overline{D}$	Power-Down pin. This active low control pin puts all DACs into power-down mode.
14	V _{DD}	Power Supply pin. This part operated from +2.5V to +5.5V.
15-24	DB ₀ -DB ₉	10 Parallel Data Inputs. DB9 is the MSB of these 10 bits.

AD5333 PIN FUNCTION DESCRIPTION





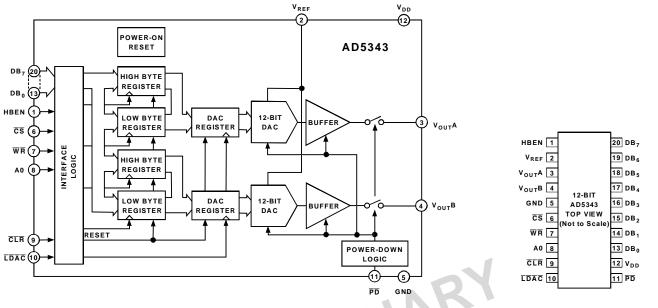
AD5342 FUNCTIONAL BLOCK DIAGRAM

AD5342 PIN CONFIGURATION

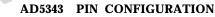
Pin No.	Mnemonic	Function					
1	GAIN	Gain control pin. This controls whether the output range from the DAC is $0\text{-}V_{REF}$ or $0\text{-}2V_{REF}$					
2	BUF	Buffer control pin. This pin controls whether the reference input to the DAC is buffered or unbuffered.					
3	V _{REF} B	Unbuffered reference input for DAC B.					
4	V _{REF} A	Unbuffered reference input for DAC A.					
5	V _{OUT} A	Output of DAC A. Buffered output with rail-to-rail operation.					
6	V _{OUT} B	Output of DAC B. Buffered output with rail-to-rail operation.					
7	NC	No Connect.					
8	NC	No Connect.					
9	GND	Ground reference point for all circuitry on the part.					
10	$\overline{C}\overline{S}$	Active low Chip Select input. This is used in conjunction with \overline{WR} to write data to the parallel interface.					
11	$\overline{W}\overline{R}$	Active low Write input. This is used in conjunction with \overline{CS} to write data to the parallel interface.					
12	A0	Address pin for selecting between DAC A and DAC B.					
13	$\overline{C}\overline{L}\overline{R}$	Asynchronous active-low control input which clears all input registers and DAC registers to zeroes.					
14	ĪDĀC	Asynchronous active-low control input which updates the DAC registers with the contents of the input registers. This allows all DAC outputs to be simultaneously updated.					
15	$\overline{P}\overline{D}$	Power-Down pin. This active low control pin puts all DACs into power-down mode.					
16	V _{DD}	Power Supply pin. This part operated from +2.5V to +5.5V.					
17-28	DB ₀ -DB ₁₁	12 Parallel Data Inputs. DB ₁₁ is the MSB of these 12 bits.					

NAN'

AD5342 PIN FUNCTION DESCRIPTION



AD5343 FUNCTIONAL BLOCK DIAGRAM



Pin No.	Mnemonic	Function						
1	HBEN	This pin is used when writing to the device to determine if data is written to the high byte register or the low byte register.						
2	V _{REF}	Jnbuffered reference input for both DACs.						
3	V _{OUT} A	Dutput of DAC A. Buffered output with rail-to-rail operation.						
4	V _{OUT} B	Output of DAC B. Buffered output with rail-to-rail operation.						
5	GND	Fround reference point for all circuitry on the part.						
6	$\overline{C}\overline{S}$	Active low Chip Select input. This is used in conjunction with \overline{WR} to write data to the parallel interface.						
7	$\overline{W}\overline{R}$	Active low Write input. This is used in conjunction with \overline{CS} to write data to the parallel interface.						
8	A0	Address pin for selecting between DAC A and DAC B.						
9	\overline{CLR}	Asynchronous active-low control input which clears all input registers and DAC registers to zeroes.						
10	<u>LDAC</u>	Asynchronous active-low control input which updates the DAC registers with the contents of the input registers. This allows all DAC outputs to be simultaneously updated.						
11	$\overline{P}\overline{D}$	Power-Down pin. This active low control pin puts all DACs into power-down mode.						
12	V _{DD}	Power Supply pin. This part operated from +2.5V to +5.5V.						
13-20	DB ₀ -DB ₇	8 Parallel Data Inputs. DB7 is the MSB of these 8 bits.						

AD5343 PIN FUNCTION DESCRIPTION

TERMINOLOGY

RELATIVE ACCURACY

For the DAC, Relative Accuracy or Integral Nonlinearity (INL) is a measure of the maximum deviation, in LSBs, from a straight line passing through the actual endpoints of the DAC transfer function. A typical INL vs. Code plot can be seen in Figure X.

DIFFERENTIAL NONLINEARITY

Differential Nonlinearity (DNL) is the difference between the measured change and the ideal 1LSB change between any two adjacent codes. A specified differential nonlinearity of \pm 1LSB maximum ensures monotonicity. This DAC is guaranteed monotonic by design. A typical DNL vs. Code plot can be seen in Figure X.

OFFSET ERROR

This is a measure of the offset error of the DAC and the output amplifier. It is expressed as a percentage of the full-scale range.

If the offset voltage is positive the output voltage will still be positive at zero input code. This is shown in Figure 3. Because the DACs operate from a single supply, a negative offset cannot appear at the output of the buffer amplifier. Instead, there will be a code close to zero at which the amplifier output saturates (amplifier footroom). Below this code there will be a deadband over which the output voltage will not change. This is illustrated in Figure 4.

GAIN ERROR

This is a measure of the span error of the DAC (including any error in the gain of the buffer amplifier). It is the deviation in slope of the actual DAC transfer characteristic from the ideal expressed as a percentage of the full-scale range. This is illustrated in Figure 2.

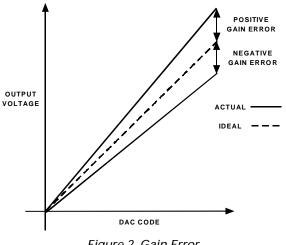
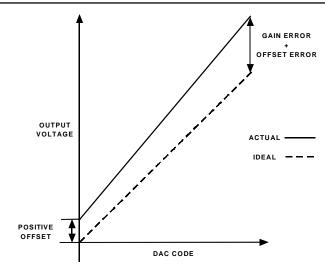
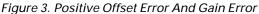


Figure 2. Gain Error





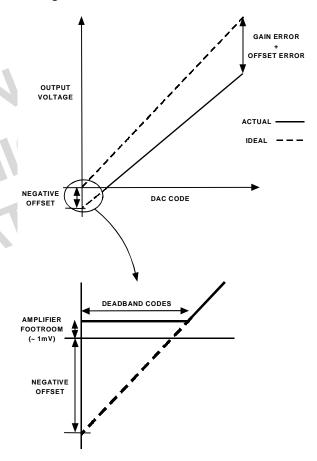


Figure 4. Negative Offset Error And Gain Error

OFFSET ERROR DRIFT

This is a measure of the change in Offset Error with changes in temperature. It is expressed in (ppm of Full-Scale Range)/ $^{\circ}$ C.

GAIN ERROR DRIFT

This is a measure of the change in Gain Error with changes in temperature. It is expressed in (ppm of full-scale range)/ $^\circ C$.

POWER-SUPPLY REJECTION RATIO (PSRR)

This indicates how the output of the DAC is affected by changes in the supply voltage. PSRR is the ratio of the change in V_{OUT} to a change in V_{DD} for full-scale output of the DAC. It is measured in dBs. V_{REF} is held at +2V and V_{DD} is varied \pm 10 %.

DC CROSSTALK

This is the DC change in the output level of one DAC at mid-scale in response to a full-scale code change (all 0s to all 1s and vice versa) and output change of the other DAC. It is expressed in μV .

REFERENCE FEEDTHROUGH

This is the ratio of the amplitude of the signal at the DAC output to the reference input when the DAC output is not being updated (i.e. $\overline{\text{LDAC}}$ is high). It is expressed in dBs.

CHANNEL-TO-CHANNEL ISOLATION

This is a ratio of the amplitude of the signal at the output of one DAC to a sine wave on the reference input of the other DAC. It is expressed in dBs.

MAJOR-CODE TRANSITION GLITCH ENERGY

Major-Code Transition Glitch Energy is the energy of the impulse injected into the analog output when the DAC changes state. It is normally specified as the area of the glitch in nV-secs and is measured when the digital code is changed by 1LSB at the major carry transition (011...11 to 100...00 or 100...00 to 011...11).

DIGITAL FEEDTHROUGH

Digital Feedthrough is a measure of the impulse injected into the analog output of the DAC from the digital input pins of the device but is measured when the DAC is not being written to $(\overline{CS}$ held high). It is specified in nV-secs and is measured with a full-scale change on the digital input pins, i.e. from all 0s to all 1s and vice versa.

DIGITAL CROSSTALK

This is the glitch impulse transferred to the output of one DAC at mid-scale in response to a full-scale code change (all 0s to all 1s and vice versa) in the input register of the other DAC. It is expressed in nV-secs.

ANALOG CROSSTALK

This is the glitch impulse transferred to the output of one DAC due to a change in the output of the other DAC. It is measured by loading one of the input registers with a full-scale code change (all 0s to all 1s and vice versa) while keeping $\overline{\text{LDAC}}$ high. Then pulse $\overline{\text{LDAC}}$ low and monitor the output of the DAC whose digital code was not changed. The area of the glitch is expressed in nV-secs.

DAC-TO-DAC CROSSTALK

This is the glitch impulse transferred to the output of one DAC due to a digital code change and subsequent output change of another DAC. This includes both digital and analog crosstalk. It is measured by loading one of the DACs with a full-scale code change (all 0s to all 1s and vice versa) with the LDAC pin set low and monitoring the output of another DAC. The energy of the glitch is expressed in nV-secs.

MULTIPLYING BANDWIDTH

The amplifiers within the DAC have a finite bandwidth. The Multiplying Bandwidth is a measure of this. A sine wave on the reference (with full-scale code loaded to the DAC) appears on the output. The Multiplying Bandwidth is the frequency at which the output amplitude falls to 3dB below the input.

TOTAL HARMONIC DISTORTION

This is the difference between an ideal sine wave and its attenuated version using the DAC. The sine wave is used as the reference for the DAC and the THD is a measure of the harmonics present on the DAC output. It is measured in dBs.

FUNCTIONAL DESCRIPTION

The AD5332/AD5333/AD5342/AD5343 are dual resistor string DACs fabricated on a CMOS process with resolutions of 8, 10, 12 and 12 bits, respectively. They are written to using a parallel interface. They operate from single supplies of +2.5V to +5.5V and the output buffer amplifiers offer rail to rail output swing. The AD5333 and AD5342 have reference inputs that may be buffered to draw virtually no current from the reference source, or unbuffered to give a reference input range from ground to V_{DD} . Their output voltage range may be configured to be 0 to V_{REF} or 0 to $2V_{REF}$. The reference inputs of the AD5332 and AD5343 are unbuffered and their output range is 0 to V_{REF} . The devices have a power-down feature that reduces current consumption to only 80nA @3V.

Digital-to-Analog Section

The architecture of one DAC channel consists of a reference buffer and a resistor-string DAC followed by an output buffer amplifier. The voltage at the V_{REF} pin provides the reference voltage for the DAC. Figure x shows a block diagram of the DAC architecture. Since the input coding to the DAC is straight binary, the ideal output voltage is given by: Voltage = Vortage X D X Gain

$$_{OUT} = V_{REF} \times \frac{D}{2^N} \times Gain$$

where:

D = decimal equivalent of the binary code which is loaded to the DAC register:

- 0-255 for AD5332 (8-bits)
- 0-1023 for AD5333/AD5342 (10-bits)
- 0-4095 for AD5343 (12-bits)
- N = DAC resolution

Gain = Output Amplifier Gain (1 or 2)

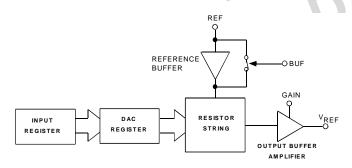
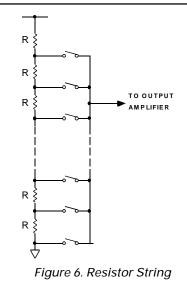


Figure 5. Single DAC Channel Architecture

Resistor String

The resistor string section is shown in Figure 6. It is simply a string of resistors, each of value R. The digital code loaded to the DAC register determines at what node on the string the voltage is tapped off to be fed into the output amplifier. The voltage is tapped off by closing one of the switches connecting the string to the amplifier. Because it is a string of resistors, it is guaranteed monotonic.



DAC Reference Inputs

The DACs operate with an external reference. The AD55332, AD5333 and AD5342 have separate reference inputs for each DAC, whilst the AD5343 has a single reference input for both DACs. The reference inputs on the AD5333 and AD5342 may be configured as buffered or unbuffered. The reference inputs of the AD5332 and AD5343 are unbuffered. The buffered/unbuffered option is controlled by the BUF pin.

In buffered mode (BUF=1) the current drawn from an external reference voltage is virtually zero, as the impedance is at least $10M\Omega$. The reference input range is 1V to 5V with a 5V supply.

In unbuffered mode (BUF=0) the user can have a reference voltage as low as GND and as high as V_{DD} since there is no restriction due to headroom and footroom of the reference amplifier. The impedance is still large at typically 180k Ω for 0-V_{REF} mode and 90k Ω for 0-2 V_{REF} mode.

If using an external buffered reference (e.g. REF192) there is no need to use the on-chip buffer.

Output Amplifier

The output buffer amplifier is capable of generating output voltages to within 1 mV of either rail. It's actual range depends on $V_{\rm REF},\ GAIN$ and offset error.

If a gain of 1 is selected (GAIN=0) the output range is 0.001 V to $V_{\text{REF}}.$

If a gain of 2 is selected (GAIN=1) on the AD5333 and AD5342 the output range is 0.001 V to $2V_{\text{REF}}.$

The output amplifier is capable of driving a load of $2k\Omega$ to GND and V_{DD} , in parallel with 500pF to an AC GND. The source and sink capabilities of the output amplifier can be seen in Figure x.

The slew rate is $0.7V/\mu s$ with a half-scale settling time to ± 0.5 LSB (at 8 bits) of 6 μs with the output unloaded. See Figure x.

PARALLEL INTERFACE

The AD5332, AD5332 and AD5342 load their data as a single 8-, 10- or 12-bit word, while the AD5343 loads data as a low byte of 8 bits and a high byte containing 4 bits.

Double-Buffered Interface

The AD5332/AD5333/AD5342/AD5343 DACs all have double-buffered interfaces consisting of an input register and a DAC register. DAC data, BUF, and GAIN inputs are written to the input register under control of the Chip Select (\overline{CS}) and Write (\overline{WR}) . LDAC is the signal which transfers data to the DAC register.

This feature allows data to be written sequentially to all DACs and peripherals without changing their outputs. Outputs of all DACs and peripherals may then be updated simultaneously using a common $\overline{\text{LDAC}}$ line. The gain and buffer control signals are also double buffered and are only updated when $\overline{\text{LDAC}}$ occurs.

Double-buffering is useful where the DAC data is loaded in two bytes, as in the AD5343, because it allows the whole data word to be assembled in parallel before updating the DAC register. This prevents spurious outputs that could occur if the DAC register was updated with only the high byte or the low byte.

Clear Input (\overline{CLR})

 $\overline{\text{CLR}}$ is an active-low, asynchronous clear that resets the input and DAC registers.

Chip Select Input (\overline{CS})

 \overline{CS} is an active-low input that selects the device.

Write Input (\overline{WR})

 \overline{WR} is an active-low input that controls writing of data to the device. Data is latched into the input register on the rising edge of \overline{WR} .

Load DAC Input (LDAC)

LDAC transfers data from the input register to the DAC register (and hence updates the outputs). Use of the LDAC function enables double buffering of the DAC data, GAIN and BUF.

There are two $\overline{\text{LDAC}}$ modes:

<u>Synchronous mode</u>: In this mode the DAC register is updated after new data is read in on the rising edge of the WR input.

<u>Asynchronous mode</u>: In this mode the outputs are not updated at the same time that the input register is written to. When $\overrightarrow{\text{LDAC}}$ goes low the DAC register is updated with the contents of the input register.

$\overline{C}\overline{L}\overline{R}$	$\overline{L}\overline{D}\overline{A}\overline{C}$	$\overline{C} \overline{S}$	$\overline{W} \overline{R}$	A0	FUNCTION
1	1	1	Х	X	No data transfer
1	1	Х	1	Х	No data transfer
0	Х	Х	Х	Х	Clear all registers
1	1	0	1→0	0	Load DAC A Input, GAIN, BUF registers
1	1	0	1→0	1	Load DAC B Input, GAIN, BUF registers
1	0	Х	Х	Х	Update DAC, GAIN, BUF

AD5332/AD5333/AD5342 TRUTH TABLE

X = don't care

AD5343 TRUTH TABLE

<u>C</u> <u>L</u> <u>R</u>	$\overline{L}\overline{D}\overline{A}\overline{C}$	$\overline{C} \overline{S}$	$\overline{W} \overline{R}$	A0	HBEN	FUNCTION
1	1	1	Х	Х	Х	No data transfer
1	1	Х	1	Х	Х	No data transfer
0	Х	Х	Х	Х	Х	Clear all registers
1	1	0	1→0	0	0	Load DAC A Low Byte Register
1	1	0	1→0	0	1	Load DAC A High Byte Register
1	1	0	1→0	1	0	Load DAC B Low Byte Register
1	1	0	1→0	1	1	Load DAC B High Byte Register
1	0	Х	Х	Х	Х	Update DAC Registers

High-Byte Enable Input (HBEN)

High-Byte Enable is a control input on the AD5343 only that determines if data is written to the high-byte input register or the low-byte input register.

The low data byte of the AD5343 consists of data bits 0 to 7 at data inputs DB_0 to DB_7 , whilst the high byte consists of data bits 8 to 11 at data inputs DB_0 to DB_3 . DB_4 to DB_7 are ignored during a high byte write, but they may be used for data to set up the reference input as buffered/ unbuffered, and buffer amplifier gain.

HIGH BYTE						
X X	Х	Х	DB11	DB10	DB9	DB8
LOW BYTE						
DB7 DB6	DB5	DB4	DB3	DB2	DB1	DB0
X = UNUSED BIT						

Figure 7. Data Format For AD5343

POWER-ON RESET

The AD5332/AD5333/AD5342/AD5343 are provided with a power-on reset function, so that they power up in a defined state. The power-on state is:

- Normal operation
- Reference input unbuffered
- 0 V_{REF} output range
- Output voltage set to 0V

Both input and DAC registers are filled with zeros and remain so until a valid write sequence is made to the device. This is particularly useful in applications where it is important to know the state of the DAC outputs while the device is powering-up.

POWER-DOWN MODE

The device can be put into a power-down mode by taking \overline{PD} low. In this mode the DAC and output amplifier are powered down. The output of the buffer amplifier is disconnected which allows the output voltage to be tied to a defined voltage using an external resistor, if required. Note that the input register can be written to in power-down mode and holds it's value when \overline{PD} is taken high. The current consumption in power-down mode is typically only 80nA @3V V_{DD} and 200nA @5V V_{DD}.

SUGGESTED DATABUS FORMATS

In most applications GAIN and BUF are hard-wired. However if more flexibility is required they can be included in a databus. This enables you to software program GAIN giving you the option to double the resolution in the lower half of the DAC range. In a bussed system GAIN and BUF may be treated as data inputs since they are written to the device during a write operation and take effect when LDAC is taken low. This means that the reference buffers and the output amplifier gain of multiple DAC devices can be controlled using common GAIN and BUF lines. The AD5333 and AD5342 databuses must be at least 10and 12- bits wide respectively and are best suited to a 16bit databus system.

Examples of data formats for putting GAIN and BUF on a 16-bit databus are shown in Figure 8. Note that any unused bits above the actual DAC data may be used for BUF and GAIN.

AD5333

X X X BUF GAIN DB9 DB8 DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0

AD5342

X X BUF GAIN DB11 DB10 DB9 DB8 DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0

X = UNUSED BIT

NAN

Figure 8. GAIN and BUF Data on a 16-bit Bus

APPLICATIONS INFORMATION

Power Supply Bypassing and Grounding

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD5332/AD5333/AD5342/AD5343 is mounted should be designed so that the analog and digital sections are separated, and confined to certain areas of the board. If the device is in a system where multiple devices require an AGND to DGND connection, the connection should be made at one point only. The star ground point should be established as closely as possible to the DUT. The AD5332/AD5333/AD5342/AD5343 should have ample supply bypassing of 10 µF in parallel with 0.1 µF on the supply located as closely to the package as possible, ideally right up against the device. The 10 μ F capacitors are the tantalum bead type. The 0.1 μ F capacitor should have low Effective Series Resistance (ESR) and Effective Series Inductance (ESI), like the common ceramic types that provide a low impedance path to ground at high frequencies to handle transient currents due to internal logic switching.

The power supply lines of the device should use as large a trace as possible to provide low impedance paths and reduce the effects of glitches on the power supply line. Fast switching signals such as clocks should be shielded with digital ground to avoid radiating noise to other parts of the board, and should never be run near the reference inputs. Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feedthrough through the board. A microstrip technique is by far the best, but not always possible with a double-sided board. In this technique, the component side of the board is dedicated to ground plane while signal traces are placed on the solder side.

Typical Application Circuits

The AD5332/AD5333/AD5342/AD5343 can be used with a wide range of reference voltages, especially if the reference inputs are configured to be unbuffered, in which case the devices offer full, one-quadrant multiplying capability over a reference range of zero to V_{DD} . More typically, these devices may be used with a fixed, precision reference voltage. Figure x shows a typical setup for the devices when using an external reference connected to the unbuffered, the reference inputs. If the reference inputs are unbuffered, the reference buffers are used, the reference range is reduced. Suitable references for 5 V operation are the AD780 and REF192. For 2.5 V operation, a suitable external reference would be the AD589, a 1.23 V bandgap reference.

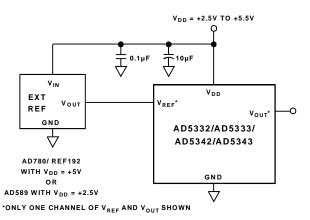
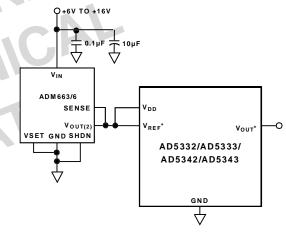


Figure 11. AD5332/AD5333/AD5342/AD5343 Using External Reference

If an output range of zero to $V_{\rm DD}$ is required when the reference inputs are configured as unbuffered (for example zero to +5V) then the simplest solution is to connect the reference inputs to $V_{\rm DD}$. As this supply may not be very accurate and may be noisy, then the devices may be powered from the reference voltage, for example using a 5V reference such as the ADM663 or ADM666, as shown in figure 8.



*ONLY ONE CHANNEL OF V_{REF} AND V_{OUT} SHOWN

Figure 12 Using an ADM663/6 as Power and Reference to AD5332/AD5333/AD5342/AD5343

Bipolar Operation Using the AD5332/AD5333/AD5342/ AD5343

The AD5332/AD5333/AD5342/AD5343 have been designed for single supply operation, but bipolar operation is achievable using the circuit shown in Figure x. The circuit shown has been configured to achieve an output voltage range of $-5 \text{ V} < \text{V}_{\text{O}} < +5 \text{ V}$. Rail-to-rail operation at the amplifier output is achievable using an AD820 or OP295 as the output amplifier.

The output voltage for any input code can be calculated as follows:

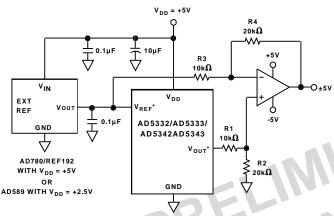
 $V_{O} = [(1 + R4/R3) \times (R2/(R1 + R2) \times (2 \times V_{REF} \times D/2^{N})] - V_{REF} \times R4/R3$ where:

D is the decimal equivalent of the code loaded to the DAC, N is DAC resolution and $V_{\rm REF}$ is the reference voltage input.

With:

 $\label{eq:VREF} \begin{array}{l} V_{REF} = 2.5 \ V \\ R1 = R3 = 10 \ k\Omega \\ R2 = R4 = 20 \ k\Omega \ and \ V_{DD} = 5 \ V. \end{array}$

$$V_{OUT} = 10 \times \underline{D} - 5 V$$



*ONLY ONE CHANNEL OF VREF AND VOUT SHOWN

Figure 13. Bipolar Operation using the AD5332/AD5333/ AD5342/AD5343

Decoding Multiple AD5332/AD5333/AD5342/AD5343

The \overline{CS} pin on these devices can be used in applications to decode a number of DACs. In this application, all DACs in the system receive the same data and \overline{WR} pulses, but only the \overline{CS} to one of the DACs will be active at any one time, so data will only be written to the DAC whose \overline{CS} is low. If multiple AD5343's are being used then a common HBEN line will also be required to determine if the data is written to the high byte- or low byte register of the selected DAC.

The 74HC139 is used as a 2- to 4-line decoder to address any of the DACs in the system. To prevent timing errors from occurring, the enable input should be brought to its inactive state while the coded address inputs are changing state. Figure 10 shows a diagram of a typical setup for decoding multiple devices in a system. Once data has been written sequentially to all DACs in a system, all the DACs can be updated simultaneously using a common LDAC line. A common $\overline{\text{CLR}}$ line can also be used to reset all DAC outputs to zero.

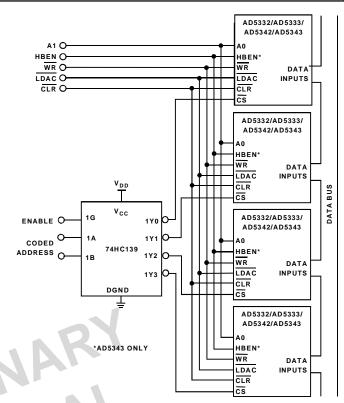


Figure 14. Decoding Multiple DAC devices

AD5332/33/42/43 as a Digitally Programmable Window Detector

A digitally programmable upper/lower limit detector using the two DACs in the AD5332/33/42/43 is shown in Figure 10. The upper and lower limits for the test are loaded to DACs A and B which, in turn, set the limits on the CMP04. If a signal at the $V_{\rm IN}$ input is not within the programmed window, a LED will indicate the fail condition.

Note that the AD5343 has only a single reference input. If using the AD5332, AD5333 or AD5342, both reference inputs must be linked.

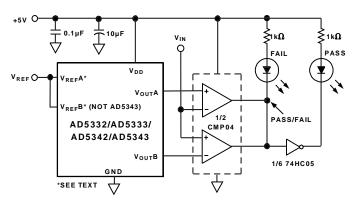


Figure 15. Programmable Window Detector

Programmable Current Source

Figure x shows the AD5332/AD5333/AD5342/AD5343 used as the control element of a programmable current source. In this example, the full-scale current is set to 1mA. The output voltage from the DAC is applied across the current setting resistor of $4.7 k\Omega$ in series with the 470 Ω adjustment potentiometer, which gives an adjustment of about $\pm 5\%$. Suitable transistors to place in the feedback loop of the amplifier include the BC107 and the 2N3904, which enable the current source to operate from a min $V_{\rm SOURCE}$ of 6 V. The operating range is determined by the operating characteristics of the transistor. Suitable amplifiers include the AD820 and the OP295, both having rail-to-rail operation on their outputs. The current for any digital input code and resistor value can be calculated as follows:

$$I = G \times V_{REF} \times \frac{D}{(2^N \times R)} mA$$

Where:

G is the gain of the buffer amplifier (1 or 2)

D is the decimal equivalent of the digital input code

N is the DAC resolution (8- 10- or 12-bits)

R is the sum of the resistor plus adjustment pot. in $k\Omega$

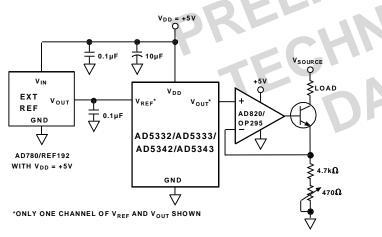


Figure 16. Programmable Current Source

Coarse and Fine Adjustment Using the AD5332/33/42/43

The DACs in the AD5332/33/42/43 can be paired together to form a coarse and fine adjustment function, as shown in figure 16. DAC A is used to provide the coarse adjustment while DAC B provides the fine adjustment. Varying the ratio of R1 and R2 will change the relative effect of the coarse and fine adjustments. With the resistor values shown the output amplifier has unity gain for the DAC A output, so the output range is zero to (V_{REF} - 1 LSB). For DAC B the amplifier has a gain of 7.6 × 10⁻³, giving DAC B a range equal 2 LSBs of DAC A.

The circuit is shown with a 2.5 V reference, but reference voltages up to $V_{\rm DD}$ may be used if the reference inputs are configured as unbuffered. The op-amps indicated will allow a rail-to-rail output swing.

Note that the AD5343 has only a single reference input. If using the AD5332, -33 or -42, both reference inputs must be linked.

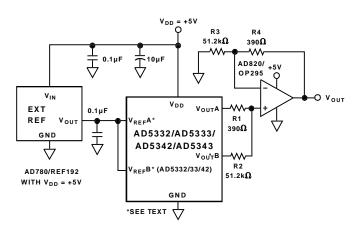


Figure 16. Coarse and Fine Adjustment

CAL

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

20-Pin TSSO Package (RU-20)

